- **Members of the Texas Instruments *Widebus*™ Family**

- ***EPIC*™ (Enhanced-Performance Implanted CMOS) Process**

- **Operating Range 2-V to 5.5-V V_{CC}**

- **Distributed V_{CC} and GND Pins Minimize High-Speed Switching Noise**

- **Flow-Through Architecture Optimizes PCB Layout**

- **Latch-Up Performance Exceeds 250 mA Per JESD 17**

- **Package Options Include Plastic Shrink Small-Outline (DL), Thin Shrink Small-Outline (DGG), and Thin Very Small-Outline (DGV) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings**

SN54AHC16541 . . . WD PACKAGE
SN74AHC16541 . . . DGG, DGV, OR DL PACKAGE
(TOP VIEW)

1$\overline{\text{OE1}}$	1	48	1$\overline{\text{OE2}}$
1Y1	2	47	1A1
1Y2	3	46	1A2
GND	4	45	GND
1Y3	5	44	1A3
1Y4	6	43	1A4
V_{CC}	7	42	V_{CC}
1Y5	8	41	1A5
1Y6	9	40	1A6
GND	10	39	GND
1Y7	11	38	1A7
1Y8	12	37	1A8
2Y1	13	36	2A1
2Y2	14	35	2A2
GND	15	34	GND
2Y3	16	33	2A3
2Y4	17	32	2A4
V_{CC}	18	31	V_{CC}
2Y5	19	30	2A5
2Y6	20	29	2A6
GND	21	28	GND
2Y7	22	27	2A7
2Y8	23	26	2A8
2$\overline{\text{OE1}}$	24	25	2$\overline{\text{OE2}}$
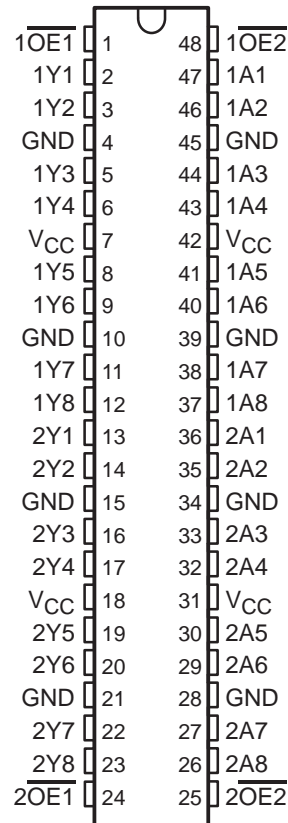
description

The 'AHC16541 devices are noninverting 16-bit buffers composed of two 8-bit sections with separate output-enable signals. For either 8-bit buffer section, the two output-enable (1$\overline{\text{OE1}}$ and 1$\overline{\text{OE2}}$ or 2$\overline{\text{OE1}}$ and 2$\overline{\text{OE2}}$) inputs must be low for the corresponding Y outputs to be active. If either output-enable input is high, the outputs of that 8-bit buffer section are in the high-impedance state.

To ensure the high-impedance state during power up or power down, $\overline{\text{OE}}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54AHC16541 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74AHC16541 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE
(each 8-bit buffer/driver)

INPUTS			OUTPUT
$\overline{\text{OE1}}$	$\overline{\text{OE2}}$	A	Y
L	L	L	L
L	L	H	H
H	X	X	Z
X	H	X	Z

EPIC and Widebus are trademarks of Texas Instruments Incorporated.

## TEXAS INSTRUMENTS

POST OFFICE BOX 655303 ● DALLAS, TEXAS 75265
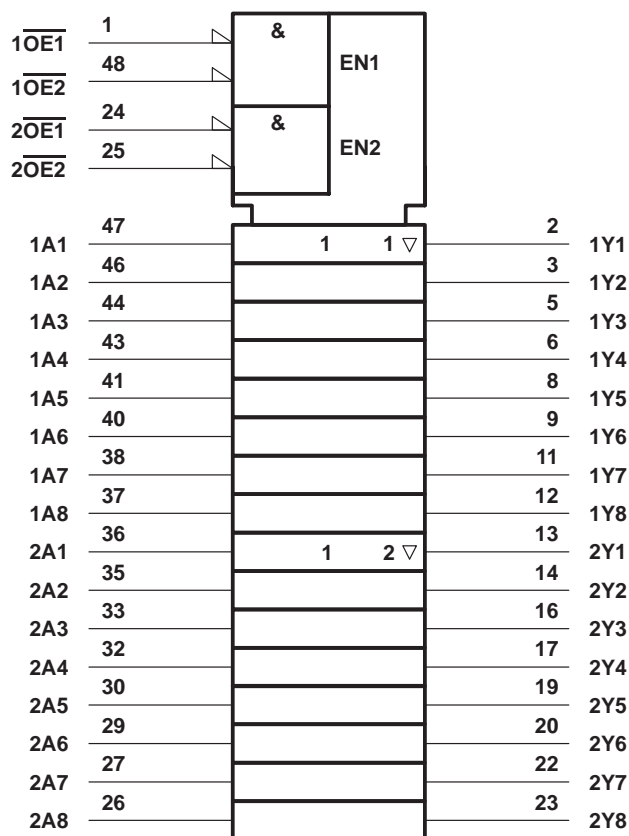
logic symbol[†]

[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)
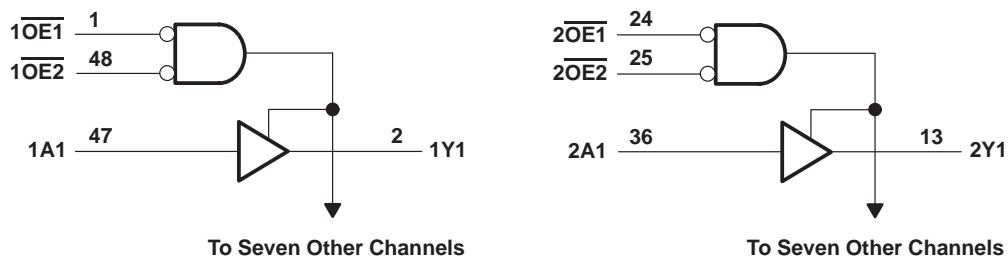
To Seven Other Channels

To Seven Other Channels

POST OFFICE BOX 655303 ● DALLAS, TEXAS 75265

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} .... –0.5 V to 7 V

Input voltage range, V_I (see Note 1) .... –0.5 V to 7 V

Output voltage range, V_O (see Note 1) .... –0.5 V to V_{CC} + 0.5 V

Input clamp current, I_{IK} ($V_I < 0$) .... –20 mA

Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) .... ±20 mA

Continuous output current, I_O ($V_O = 0$ to V_{CC}) .... ±25 mA

Continuous current through each V_{CC} or GND .... ±75 mA

Package thermal impedance, θ_{JA} (see Note 2): DGG package .... 70°C/W

DGV package .... 58°C/W

DL package .... 63°C/W

Storage temperature range, T_{stg} .... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 3)

			SN54AHC16541		SN74AHC16541		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		2	5.5	2	5.5	V
V_{IH}	High-level input voltage	V_{CC} = 2 V	1.5		1.5		V
		V_{CC} = 3 V	2.1		2.1		
		V_{CC} = 5.5 V	3.85		3.85		
V_{IL}	Low-level input voltage	V_{CC} = 2 V		0.5		0.5	V
		V_{CC} = 3 V		0.9		0.9	
		V_{CC} = 5.5 V		1.65		1.65	
V_I	Input voltage		0	5.5	0	5.5	V
V_O	Output voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current	V_{CC} = 2 V		–50		–50	μA
		V_{CC} = 3.3 V ± 0.3 V		–4		–4	mA
		V_{CC} = 5 V ± 0.5 V		–8		–8	
I_{OL}	Low-level output current	V_{CC} = 2 V		50		50	μA
		V_{CC} = 3.3 V ± 0.3 V		4		4	mA
		V_{CC} = 5 V ± 0.5 V		8		8	
$\Delta t/\Delta v$	Input transition rise or fall rate	V_{CC} = 3.3 V ± 0.3 V		100		100	ns/V
		V_{CC} = 5 V ± 0.5 V		20		20	
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

TEXAS INSTRUMENTS

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	$T_A = 25°C$			SN54AHC16541		SN74AHC16541		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}	$I_{OH} = -50\ \mu A$	2 V	1.9	2		1.9		1.9		V
		3 V	2.9	3		2.9		2.9		
		4.5 V	4.4	4.5		4.4		4.4		
	$I_{OH} = -4\ mA$	3 V	2.58			2.48		2.48		
	$I_{OH} = -8\ mA$	4.5 V	3.94			3.8		3.8		
V_{OL}	$I_{OL} = 50\ \mu A$	2 V			0.1		0.1		0.1	V
		3 V			0.1		0.1		0.1	
		4.5 V			0.1		0.1		0.1	
	$I_{OL} = 4\ mA$	3 V			0.36		0.5		0.44	
	$I_{OL} = 8\ mA$	4.5 V			0.36		0.5		0.44	
I_I	$V_I = V_{CC}$ or GND	0 V to 5.5 V			±0.1		±1*		±1	μA
I_{OZ}	$V_O = V_{CC}$ or GND, V_I ($\overline{OE}$) = V_{IL} or V_{IH}	5.5 V			±0.25		±2.5		±2.5	μA
I_{CC}	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			4		40		40	μA
C_i	$V_I = V_{CC}$ or GND	5 V		2	10				10	pF
C_o	$V_O = V_{CC}$ or GND	5 V		3						pF

* On products compliant to MIL-PRF-38535, this parameter is not production tested at $V_{CC} = 0$ V.

switching characteristics over recommended operating free-air temperature range, $V_{CC} = 3.3\ V \pm 0.3\ V$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	$T_A = 25°C$			SN54AHC16541		SN74AHC16541		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A	Y	$C_L = 15$ pF		5**	8.4**	1**	10**	1	10	ns
t_{PHL}					5**	8.4**	1**	10**	1	10	
t_{PZH}	$\overline{OE}$	Y	$C_L = 15$ pF		6**	10.6**	1**	12.5**	1	12.5	ns
t_{PZL}					6**	10.6**	1**	12.5**	1	12.5	
t_{PHZ}	$\overline{OE}$	Y	$C_L = 15$ pF		7**	11.5**	1**	12.5**	1	12.5	ns
t_{PLZ}					7**	11.5**	1**	12.5**	1	12.5	
t_{PLH}	A	Y	$C_L = 50$ pF		7.5	11.9	1	13.5	1	13.5	ns
t_{PHL}					7.5	11.9	1	13.5	1	13.5	
t_{PZH}	$\overline{OE}$	Y	$C_L = 50$ pF		8	14.1	1	16	1	16	ns
t_{PZL}					8	14.1	1	16	1	16	
t_{PHZ}	$\overline{OE}$	Y	$C_L = 50$ pF		9	14	1	16	1	16	ns
t_{PLZ}					9	14	1	16	1	16	
$t_{sk(o)}$			$C_L = 50$ pF			1.5***				1.5	ns

** On products compliant to MIL-PRF-38535, this parameter is not production tested.
*** On products compliant to MIL-PRF-38535, this parameter does not apply.

TEXAS
INSTRUMENTS

switching characteristics over recommended operating free-air temperature range,
V_{CC} = 5 V $\pm$ 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T_A = 25°C			SN54AHC16541		SN74AHC16541		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A	Y	C_L = 15 pF		3.5*	6*	1*	7*	1	6.5	ns
t_{PHL}					3.5*	6*	1*	7*	1	6.5	
t_{PZH}	$\overline{OE}$	Y	C_L = 15 pF		4.7*	7.3*	1*	8.5*	1	8.5	ns
t_{PZL}					4.7*	7.3*	1*	8.5*	1	8.5	
t_{PHZ}	$\overline{OE}$	Y	C_L = 15 pF		5*	7.2*	1*	8.5*	1	8.5	ns
t_{PLZ}					5*	7.2*	1*	8.5*	1	8.5	
t_{PLH}	A	Y	C_L = 50 pF		5	8	1	9	1	8.5	ns
t_{PHL}					5	8	1	9	1	8.5	
t_{PZH}	$\overline{OE}$	Y	C_L = 50 pF		6.2	9.3	1	10.5	1	10.5	ns
t_{PZL}					6.2	9.3	1	10.5	1	10.5	
t_{PHZ}	$\overline{OE}$	Y	C_L = 50 pF		6	9.2	1	10.5	1	10.5	ns
t_{PLZ}					6	9.2	1	10.5	1	10.5	
$t_{sk(o)}$			C_L = 50 pF		1**					1	ns

* On products compliant to MIL-PRF-38535, this parameter is not production tested.
** On products compliant to MIL-PRF-38535, this parameter does not apply.

noise characteristics, V_{CC} = 5 V, C_L = 50 pF, T_A = 25°C (see Note 4)

PARAMETER		SN74AHC16541			UNIT
		MIN	TYP	MAX	
$V_{OL(P)}$	Quiet output, maximum dynamic V_{OL}		0.7		V
$V_{OL(V)}$	Quiet output, minimum dynamic V_{OL}		−0.3		V
$V_{OH(V)}$	Quiet output, minimum dynamic V_{OH}		4.7		V
$V_{IH(D)}$	High-level dynamic input voltage	3.5			V
$V_{IL(D)}$	Low-level dynamic input voltage			1.5	V

NOTE 4:   Characteristics are for surface-mount packages only.

operating characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER		TEST CONDITIONS		TYP	UNIT
C_{pd}	Power dissipation capacitance	No load,	f = 1 MHz	12	pF

TEXAS
INSTRUMENTS

POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

PARAMETER MEASUREMENT INFORMATION

From Output Under Test — Test Point

C_L (see Note A)

LOAD CIRCUIT FOR TOTEM-POLE OUTPUTS

From Output Under Test — $R_L = 1\ k\Omega$ — S1 — V_{CC} / Open / GND

C_L (see Note A)

LOAD CIRCUIT FOR 3-STATE AND OPEN-DRAIN OUTPUTS

TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	V_{CC}
t_{PHZ}/t_{PZH}	GND
Open Drain	V_{CC}

Input — t_w — 50% V_{CC} — 50% V_{CC} — V_{CC} / 0 V

**VOLTAGE WAVEFORMS
PULSE DURATION**

Timing Input — 50% V_{CC} — V_{CC} / 0 V — t_h

t_{su}

Data Input — 50% V_{CC} — 50% V_{CC} — V_{CC} / 0 V

**VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES**

Input — 50% V_{CC} — 50% V_{CC} — V_{CC} / 0 V

t_{PLH} — t_{PHL}

In-Phase Output — 50% V_{CC} — 50% V_{CC} — V_{OH} / V_{OL}

t_{PHL} — t_{PLH}

Out-of-Phase Output — 50% V_{CC} — 50% V_{CC} — V_{OH} / V_{OL}

**VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS**

Output Control — 50% V_{CC} — 50% V_{CC} — V_{CC} / 0 V

t_{PZL} — t_{PLZ}

Output Waveform 1 S1 at V_{CC} (see Note B) — 50% V_{CC} — $\approx V_{CC}$ / V_{OL} + 0.3 V / V_{OL}

t_{PZH} — t_{PHZ}

Output Waveform 2 S1 at GND (see Note B) — 50% V_{CC} — V_{OH} / V_{OH} − 0.3 V / ≈ 0 V

**VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING**

NOTES: A. C_L includes probe and jig capacitance.
  B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control.
     Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
  C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, $Z_O = 50\ \Omega$, t_r ≤ 3 ns, t_f ≤ 3 ns.
  D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
74AHC16541DGGRE4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AHC16541DGGRG4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AHC16541DGVRE4	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AHC16541DGVRG4	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC16541DGGR	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC16541DGVR	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC16541DL	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC16541DLG4	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC16541DLR	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC16541DLRG4	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check
http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

PACKAGE MATERIALS INFORMATION

TAPE AND REEL INFORMATION

REEL DIMENSIONS

TAPE DIMENSIONS

A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AHC16541DGGR	TSSOP	DGG	48	2000	330.0	24.4	8.6	15.8	1.8	12.0	24.0	Q1
SN74AHC16541DGVR	TVSOP	DGV	48	2000	330.0	16.4	7.1	10.2	1.6	12.0	16.0	Q1
SN74AHC16541DLR	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1

TAPE AND REEL BOX DIMENSIONS

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AHC16541DGGR	TSSOP	DGG	48	2000	346.0	346.0	41.0
SN74AHC16541DGVR	TVSOP	DGV	48	2000	346.0	346.0	33.0
SN74AHC16541DLR	SSOP	DL	48	1000	346.0	346.0	49.0

DGG (R-PDSO-G)**   **PLASTIC SMALL-OUTLINE PACKAGE**

48 PINS SHOWN

PINS ** DIM	48	56	64
A MAX	12,60	14,10	17,10
A MIN	12,40	13,90	16,90

4040078 / F 12/97

NOTES: A. All linear dimensions are in millimeters.
        B. This drawing is subject to change without notice.
        C. Body dimensions do not include mold protrusion not to exceed 0,15.
        D. Falls within JEDEC MO-153

**TEXAS
INSTRUMENTS**

DL (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN

0.025 (0,635)

0.0135 (0,343) / 0.008 (0,203)

⊕ 0.005 (0,13) Ⓜ

48   25

0.299 (7,59) / 0.291 (7,39)

0.420 (10,67) / 0.395 (10,03)

1   24

A

0.010 (0,25) / 0.005 (0,13)

Gage Plane

0°–8°

0.010 (0,25)

0.040 (1,02) / 0.020 (0,51)

0.110 (2,79) MAX   0.008 (0,20) MIN

Seating Plane

◠ 0.004 (0,10)

DIM \ PINS **	28	48	56
A MAX	0.380 (9,65)	0.630 (16,00)	0.730 (18,54)
A MIN	0.370 (9,40)	0.620 (15,75)	0.720 (18,29)

4040048 / E 12/01
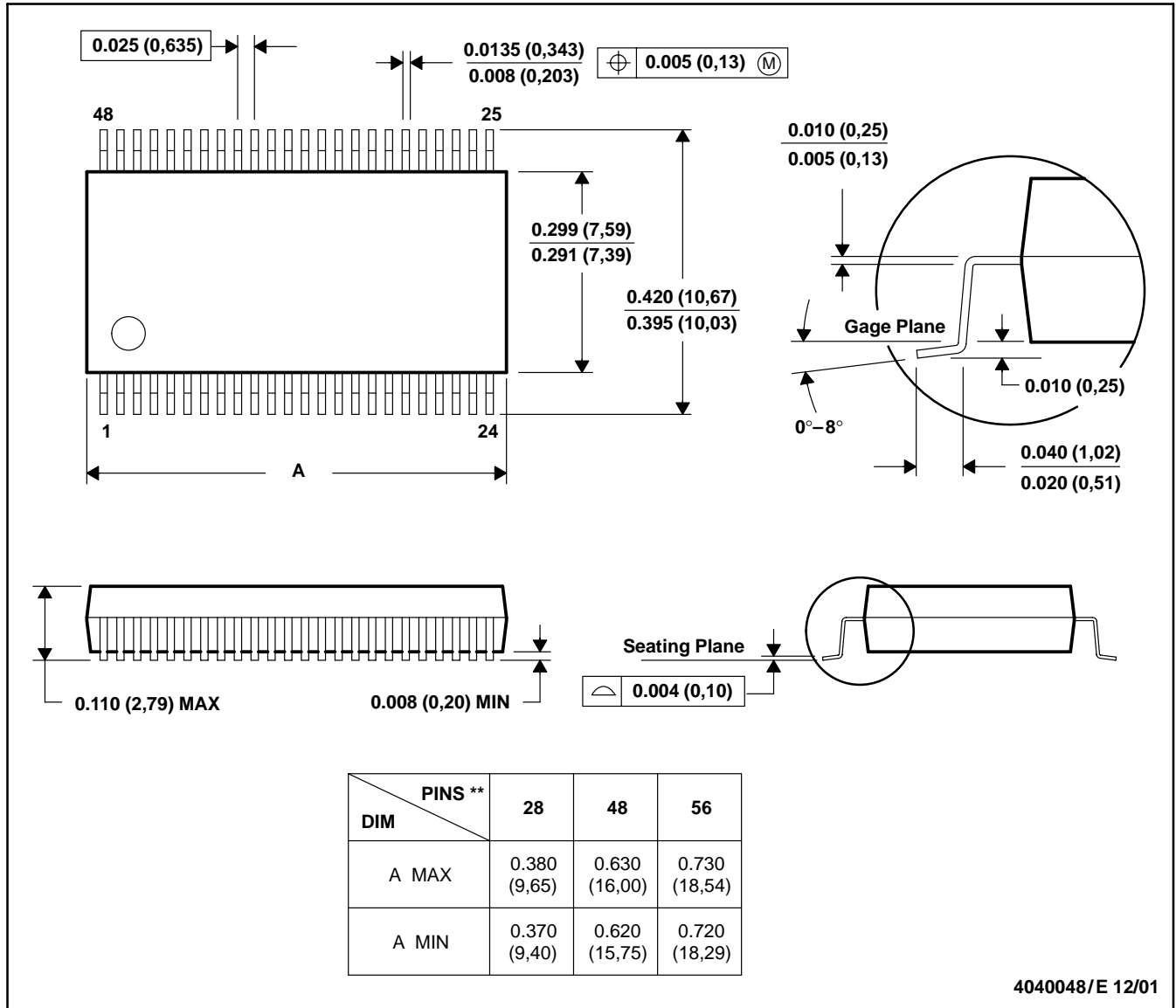
NOTES: A. All linear dimensions are in inches (millimeters).
        B. This drawing is subject to change without notice.
        C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
        D. Falls within JEDEC MO-118

TEXAS INSTRUMENTS

POST OFFICE BOX 655303 ● DALLAS, TEXAS 75265

DGV (R-PDSO-G**)　　　　　　　　　　　　　　　　　　**PLASTIC SMALL-OUTLINE**

24 PINS SHOWN

PINS ** DIM	14	16	20	24	38	48	56
A MAX	3,70	3,70	5,10	5,10	7,90	9,80	11,40
A MIN	3,50	3,50	4,90	4,90	7,70	9,60	11,20

4073251/E 08/00

NOTES: A. All linear dimensions are in millimeters.
　　　　B. This drawing is subject to change without notice.
　　　　C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
　　　　D. Falls within JEDEC: 24/48 Pins – MO-153
　　　　　　　　　　　　　　14/16/20/56 Pins – MO-194

TEXAS INSTRUMENTS

POST OFFICE BOX 655303 ● DALLAS, TEXAS 75265

IMPORTANT NOTICE